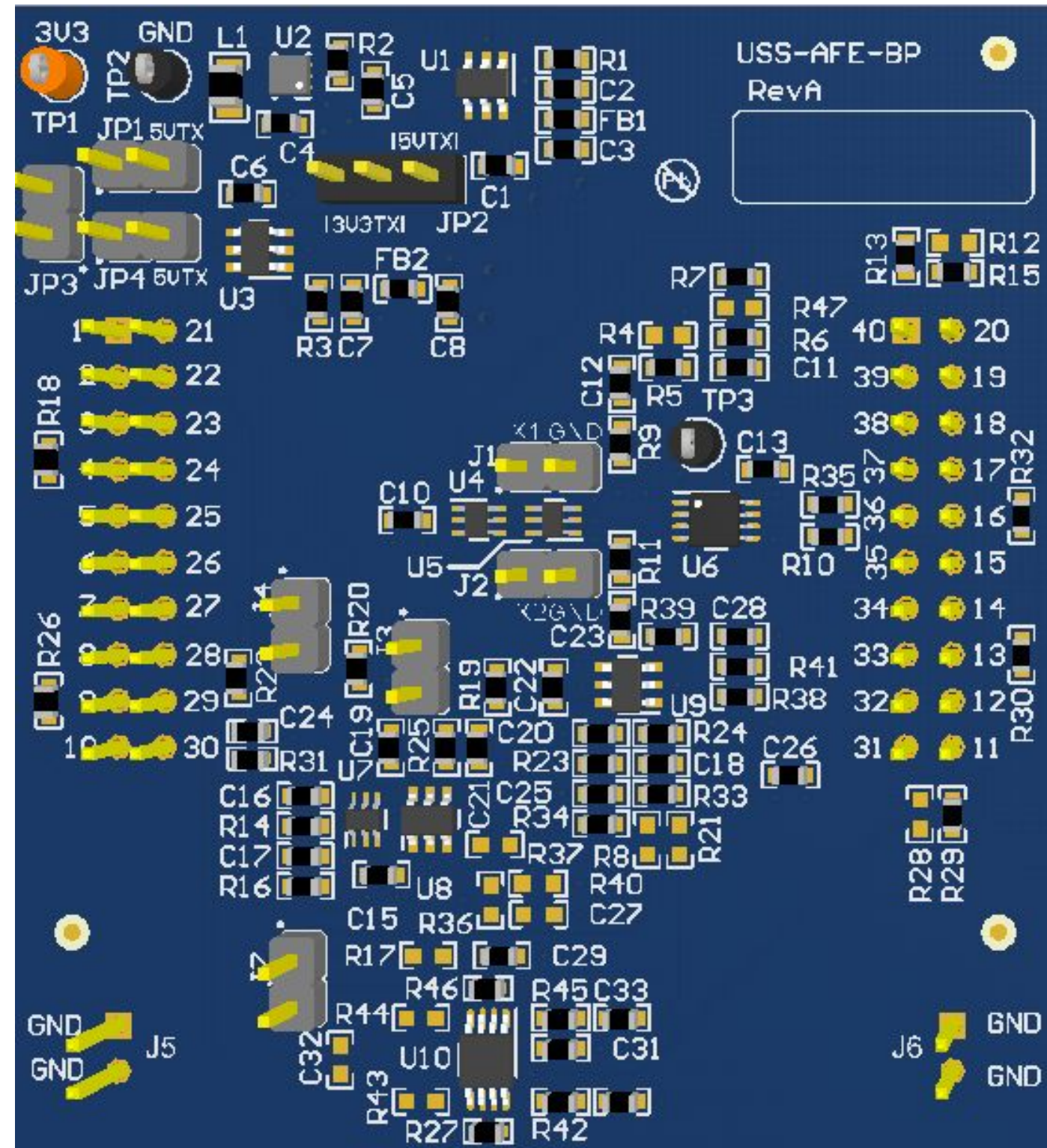


Revision History

Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A

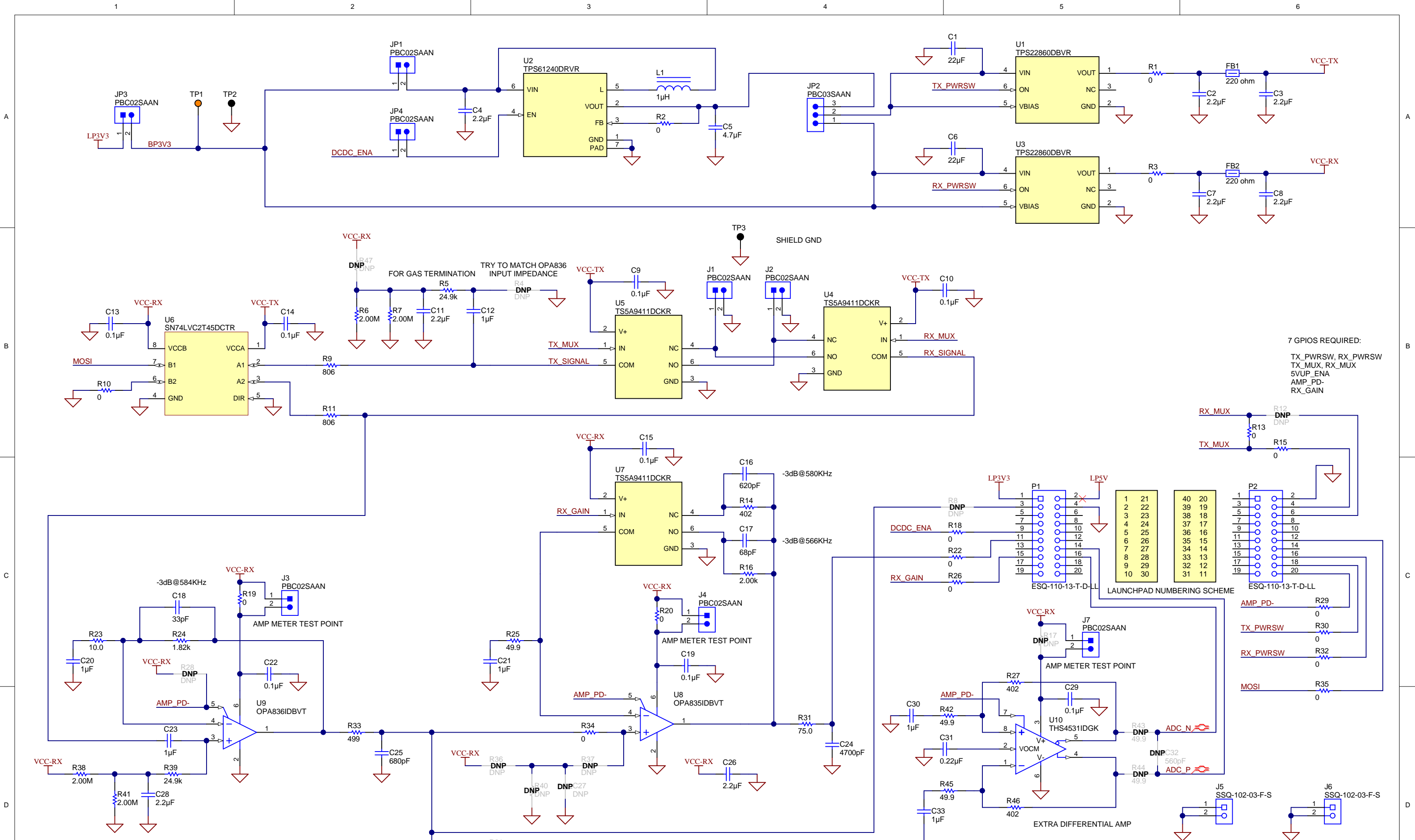


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Orderable: USS-AFE-BP	Designed for: Public Release	Mod. Date: 5/31/2017
TID #: TIDM-1002	Project Title: USS-AFE-BP	
Number: USS-AFE-BP Rev: 1.0	Sheet Title: Cover Sheet	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 3
Drawn By:	File: USS_AFE_BP_CoverSheet.SchDoc	Size: B
Engineer: Luis Reynoso	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



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**DNP**  
FID1

**DNP**  
FID2

**DNP**  
FID3

PCB Number: USS-AFE-BP  
PCB Rev: RevA

PCB LOGO  
Pb-Free Symbol

PCB LOGO  
FCC disclaimer

Label Table

Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1  
**DNP**  
Size: 0.65" x 0.20"

ZZ1  
**Label Assembly Note**  
This Assembly Note is for PCB labels only

ZZ2  
**Assembly Note**  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
**Assembly Note**  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
**Assembly Note**  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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